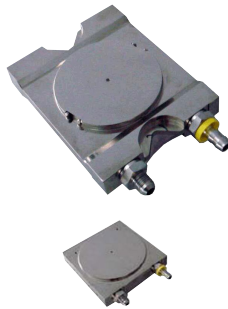


Aluminium Press Pack

LIQUID COOLED HEATSINKS

ALUMINIUM



Mersen aluminium Press Pack provides the maximum thermal performance in employing proprietary channeling techniques to optimize coolant velocity at low pressure drop while providing uniform temperature across the mounting surface for semiconductor reliability.

It is an effective and reliable solution. Liquid cooled systems work perfectly for power electronics components, especially when installed in a confined space.

Mersen is expert in vacuum brazing technology which ensure maximum reliability: guaranteed water tightness with no leak, robustness, no corrosion and excellent thermal performance. Result: a product sure to last decades!

FEATURES & BENEFITS

- 100% aluminium (alloy)
- High thermal performance (cost cutting with no derating of power module)
- Low pressure drop compared to similar product
- Homogeneous temperature distribution below semiconductor
- Very high pressure withstanding guarantee
- Perfect water tightness with no risk of leak
- All cold plates systematically pressure tested at 100%
- Vacuum brazing technology means no corrosion: flux free!
- Long life time: >20 years guaranteed
- Options:
 - Surface coating
 - Tab for electrical connections
 - Fitting as per customer requirements

APPLICATIONS

- Cooling of any size of press pack semiconductor

STANDARDS

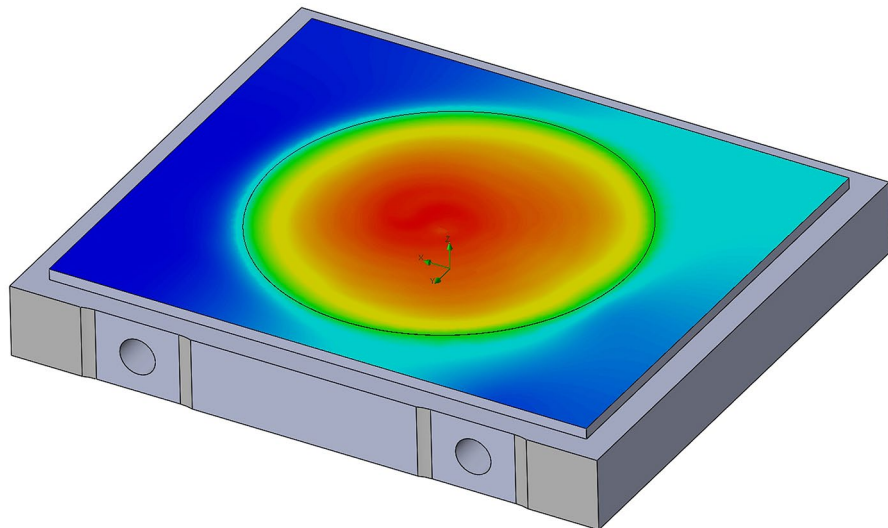
- Vacuum-brazing technology
- RoHS compliant



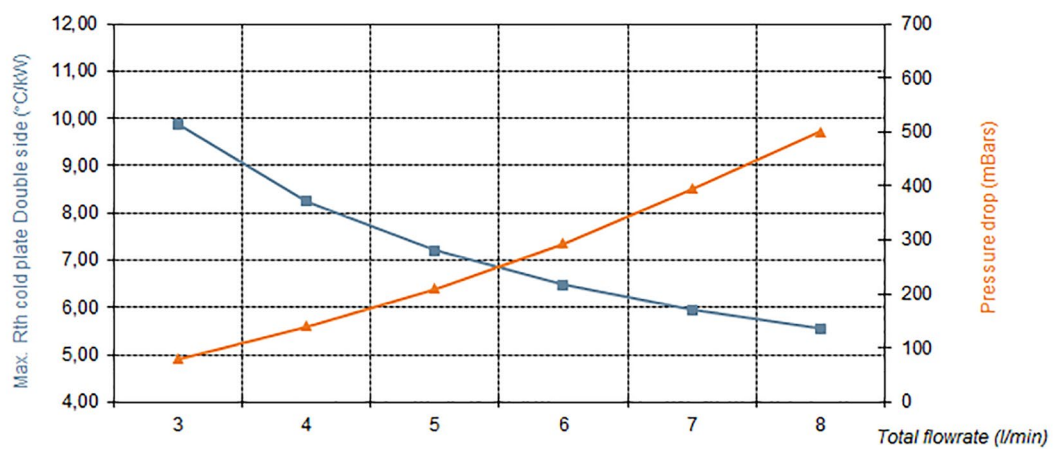
Aluminium Press Pack

THERMAL AND HYDRAULIC PERFORMANCES

Perfect homogeneous temperature distribution below semiconductor for high reliability



Semiconductor contact surface diameter: 85mm

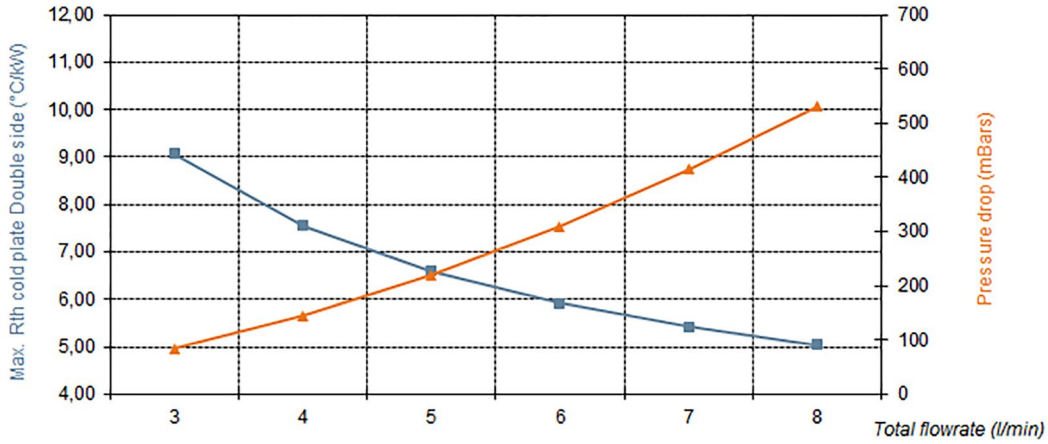


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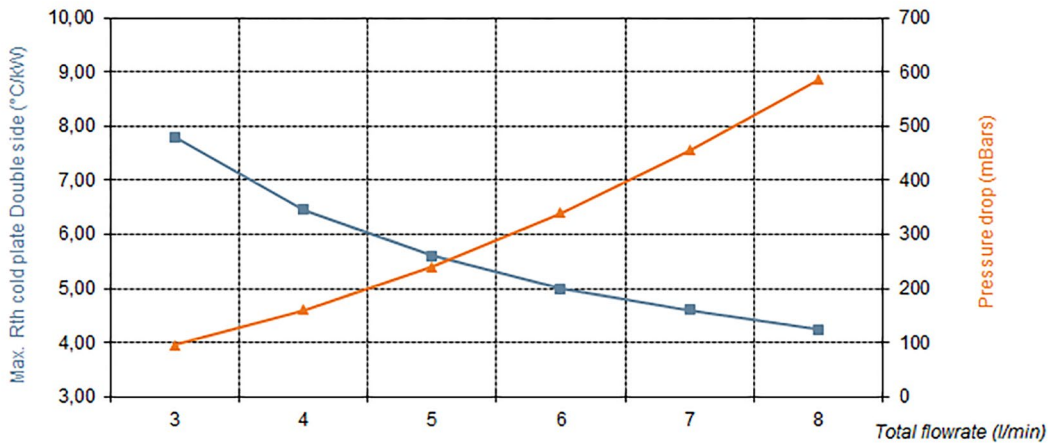
Aluminium Press Pack

THERMAL AND HYDRAULIC PERFORMANCES

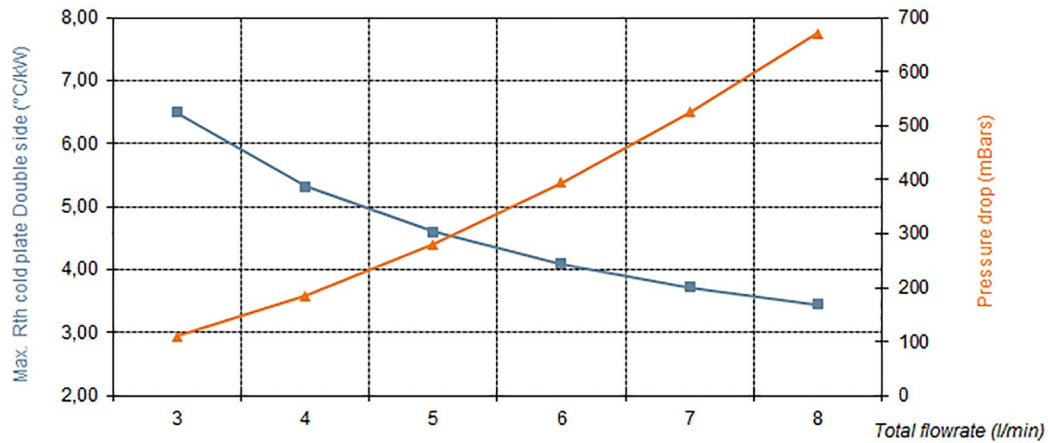
Semiconductor contact surface diameter: 90mm



Semiconductor contact surface diameter: 100mm



Semiconductor contact surface diameter: 115mm

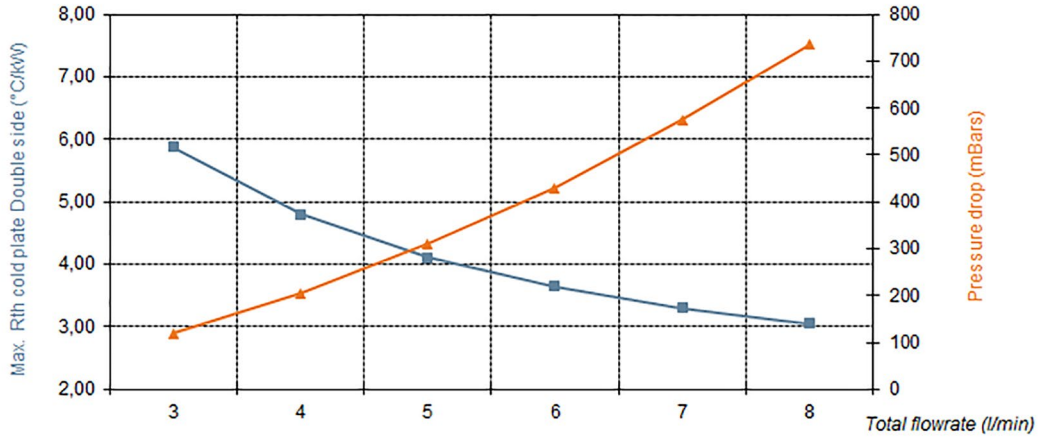


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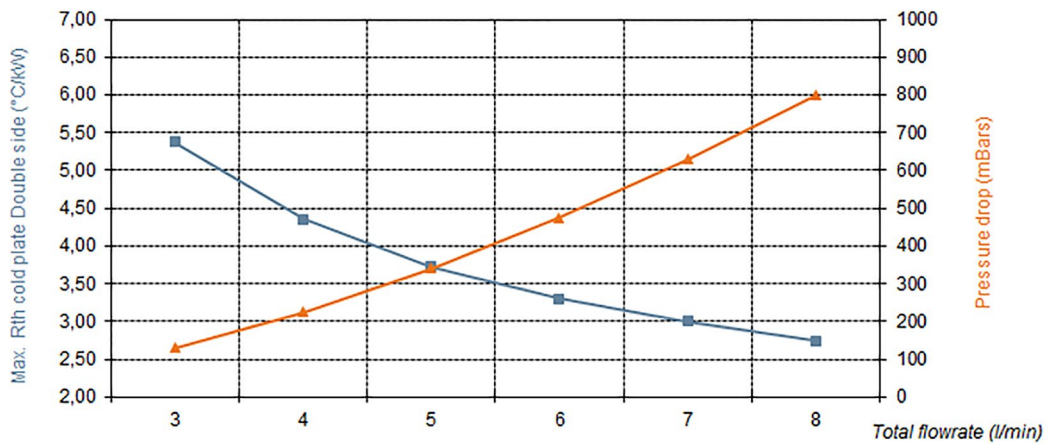
Aluminium Press Pack

THERMAL AND HYDRAULIC PERFORMANCES

Semiconductor contact surface diameter: 125mm

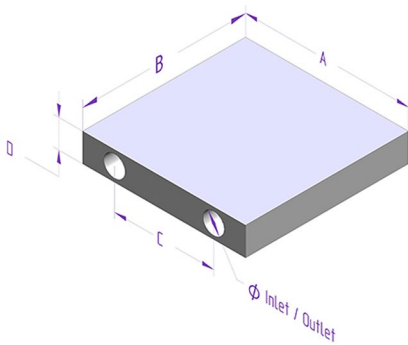


Semiconductor contact surface diameter: 135mm



DIMENSIONS

Contact view



\varnothing Component	A	B	C	D
\varnothing 85	110	110	70	\varnothing Inlet / Outlet + 5 mm
\varnothing 90	115	115	70	\varnothing Inlet / Outlet + 5 mm
\varnothing 100	125	125	80	\varnothing Inlet / Outlet + 5 mm
\varnothing 115	140	140	80	\varnothing Inlet / Outlet + 5 mm
\varnothing 125	150	150	100	\varnothing Inlet / Outlet + 5 mm
\varnothing 135	160	160	100	\varnothing Inlet / Outlet + 5 mm